DZ4J091K

Silicon epitaxial planar type

For constant voltage / waveform clipper and surge absorption circuit
Low noise type

■ Features

- Excellent rising characteristics of zener current I_z
- Eco-friendly Halogen-free package

■ Basic Part Number

Double DZ2J091 (Parallel)

■ Packaging

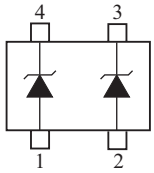
Embossed type (Thermo-compression sealing): 3000 pcs / reel (standard)

■ Package

- Code
  SMini4-F3-B
- Pin Name
  1: Anode-1 3: Cathode-2
  2: Anode-2 4: Cathode-1

■ Marking Symbol: LJ

■ Internal Connection



■ Absolute Maximum Ratings $T_a = 25°C$

Parameter	Symbol	Rating	Unit
Repetitive peak forward current	I_{FRM}	200	mA
Total power dissipation *	P_T	200	mW
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	–55 to +150	°C

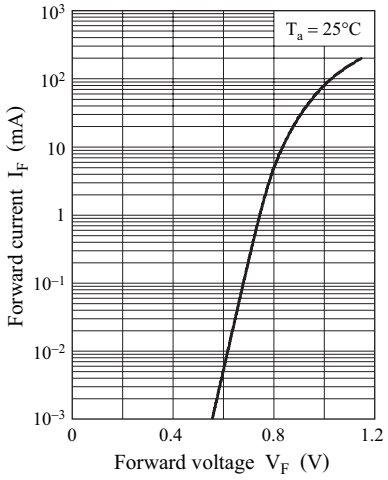
Note) ∗: P_T = 200 mW achieved with a printed circuit board.

■ Common Electrical Characteristics $T_a = 25°C \pm 3°C$

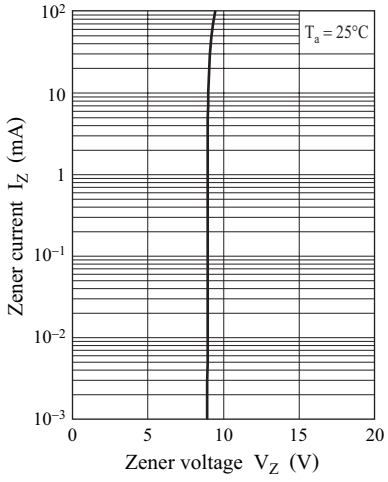
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	I_F = 10 mA			1.0	V
Zener voltage *1, 2	V_Z	I_Z = 5 mA	8.65		9.56	V
Zener operating resistance	R_Z	I_Z = 5 mA			20	Ω
Zener rise operating resistance	R_{ZK}	I_Z = 0.5 mA			60	Ω
Reverse current	I_R	V_R = 6 V			0.1	μA
Temperature coefficient of zener voltage *3	S_Z	I_Z = 5 mA		5.8		mV/°C

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
2. Absolute frequency of input and output is 5 MHz.
3. ∗1: The temperature must be controlled 25°C for V_Z measurement. V_Z value measured at other temperature must be adjusted to V_Z (25°C)
∗2: V_Z guaranteed 20 ms after current flow.
∗3: T_j = 25°C to 150°C

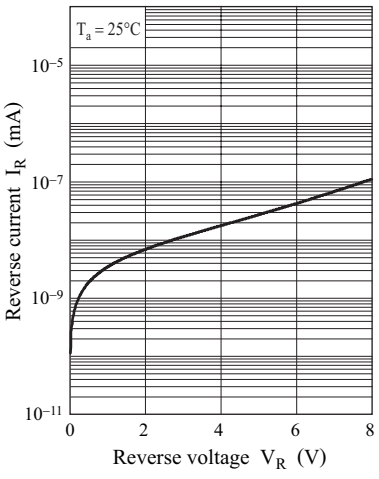
I_F — V_F



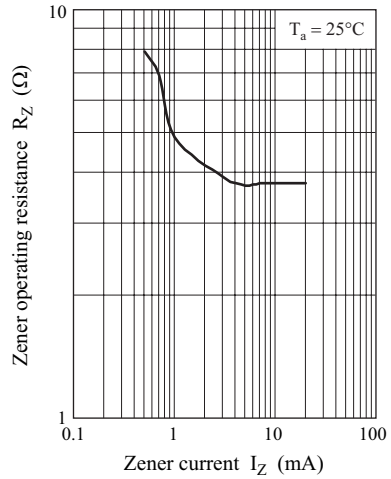
I_Z — V_Z



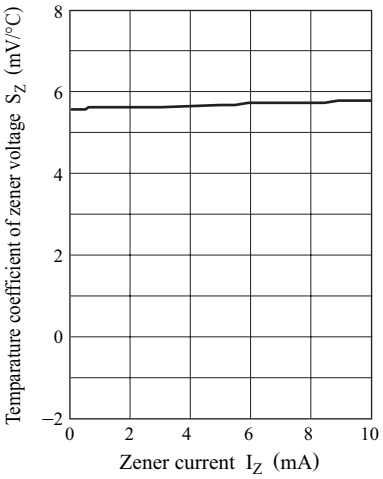
I_R — V_R



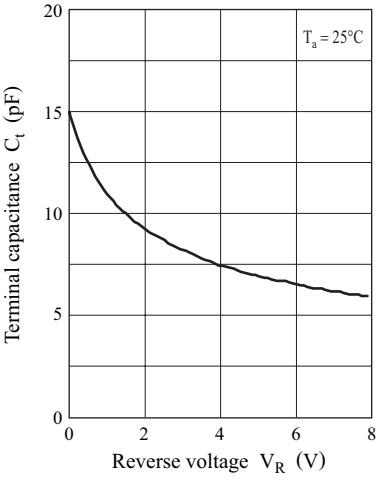
R_Z — I_Z



S_Z — I_Z

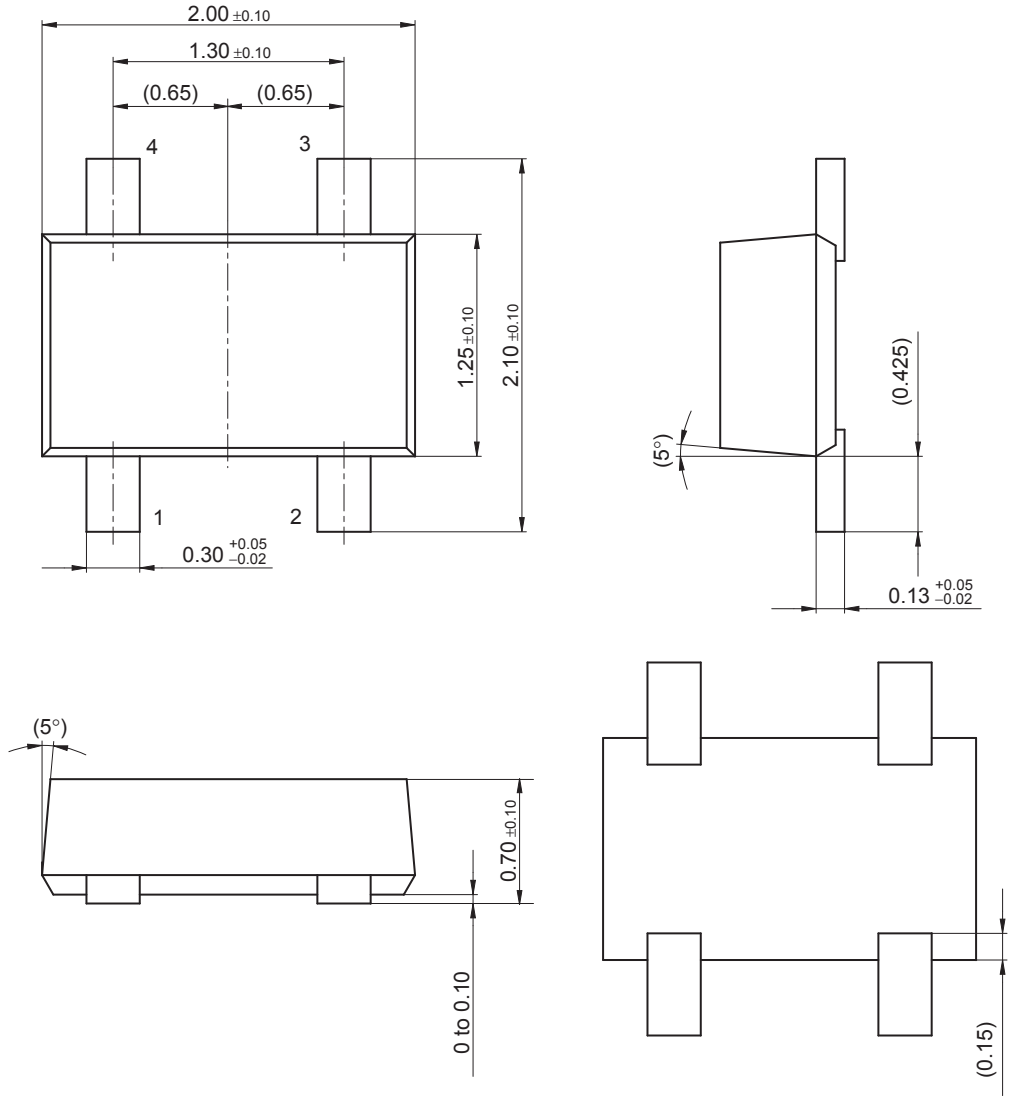


C_t — V_R



SMini4-F3-B

Unit: mm



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